

SN54HC74, SN74HC74 DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

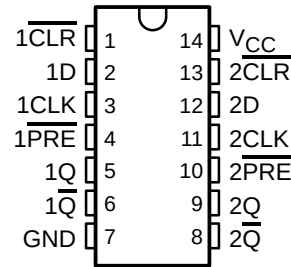
SCLS094D – DECEMBER 1982 – REVISED JULY 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 40- μ A Max I_{CC}
- Typical $t_{pd} = 15$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max

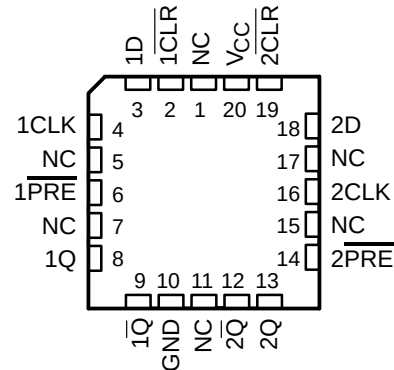
description/ordering information

The 'HC74 devices contain two independent D-type positive-edge-triggered flip-flops. A low level at the preset ($\overline{PRE}$) or clear ($\overline{CLR}$) inputs sets or resets the outputs, regardless of the levels of the other inputs. When $\overline{PRE}$ and $\overline{CLR}$ are inactive (high), data at the data (D) input meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of CLK. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

SN54HC74 . . . J OR W PACKAGE
SN74HC74 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC74 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T _A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HC74N	SN74HC74N
	SOIC – D	Tube of 50	SN74HC74D	HC74
		Reel of 2500	SN74HC74DR	
		Reel of 250	SN74HC74DT	
	SOP – NS	Reel of 2000	SN74HC74NSR	HC74
	SSOP – DB	Reel of 2000	SN74HC74DBR	HC74
	TSSOP – PW	Tube of 90	SN74HC74PW	HC74
		Reel of 2000	SN74HC74PWR	
		Reel of 250	SN74HC74PWT	
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC74J	SNJ54HC74J
	CFP – W	Tube of 150	SNJ54HC74W	SNJ54HC74W
	LCCC – FK	Tube of 55	SNJ54HC74FK	SNJ54HC74FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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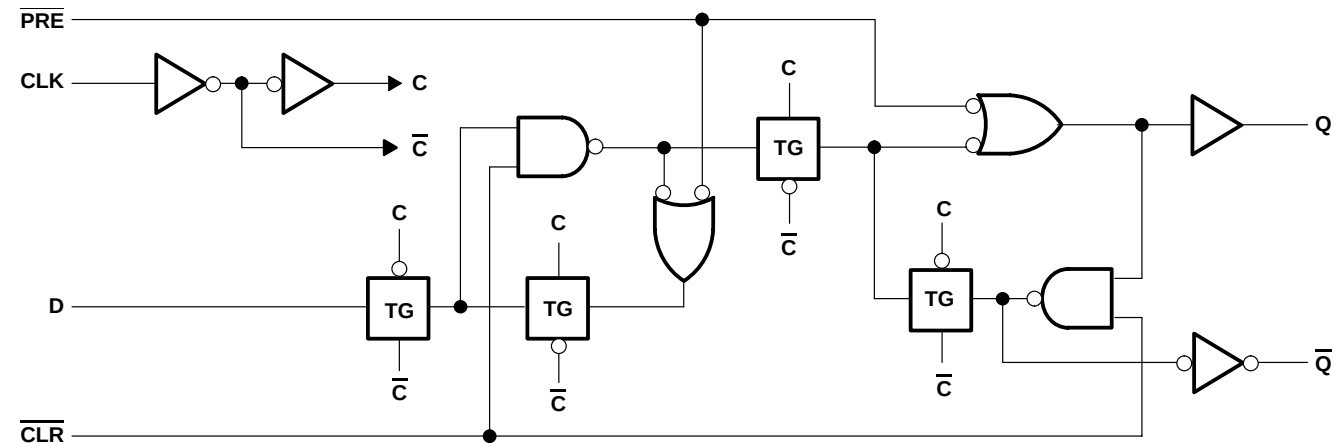
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FUNCTION TABLE

INPUTS				OUTPUTS	
PRE	CLR	CLK	D	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H [†]	H [†]
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q ₀	$\overline{Q}_0$

[†] This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	86°C/W
DB package	96°C/W
N package	80°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[‡] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Note 3)

			SN54HC74			SN74HC74			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5			1.5			V
		V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 6 V	4.2			4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5			0.5			V
		V _{CC} = 4.5 V	1.35			1.35			
		V _{CC} = 6 V	1.8			1.8			
V _I	Input voltage		0	V _{CC}		0	V _{CC}		V
V _O	Output voltage		0	V _{CC}		0	V _{CC}		V
$\Delta t/\Delta v$	Input transition rise/fall time	V _{CC} = 2 V	1000			1000			ns
		V _{CC} = 4.5 V	500			500			
		V _{CC} = 6 V	400			400			
T _A	Operating free-air temperature		−55		125	−40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC74		SN74HC74		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = –20 µA	2 V	1.9	1.998		1.9		1.9		V
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I _{OH} = –4 mA	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = –5.2 mA	6 V	5.48	5.8		5.2		5.34		
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 µA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
I _I	V _I = V _{CC} or 0		6 V		±0.1	±100		±1000		±1000	nA
I _{CC}	V _I = V _{CC} or 0, I _O = 0		6 V			4		80		40	µA
C _i			2 V to 6 V		3	10		10		10	pF



SN54HC74, SN74HC74

DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25°C		SN54HC74		SN74HC74		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	2 V	6		4.2		5		MHz
		4.5 V	31		21		25		
		6 V	0	36	0	25	0	29	
t _w	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	2 V	100		150		125		ns
		4.5 V	20		30		25		
		6 V	17		25		21		
	CLK high or low	2 V	80		120		100		
		4.5 V	16		24		20		
		6 V	14		20		17		
t _{su}	Data	2 V	100		150		125		ns
		4.5 V	20		30		25		
		6 V	17		25		21		
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	2 V	25		40		30		
		4.5 V	5		8		6		
		6 V	4		7		5		
t _h	Hold time, data after CLK↑	2 V	0		0		0		ns
		4.5 V	0		0		0		
		6 V	0		0		0		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC74		SN74HC74		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			2 V	6	10		4.2		5		MHz
			4.5 V	31	50		21		25		
			6 V	36	60		25		29		
t _{pd}	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or $\overline{\text{Q}}$	2 V		70	230		345		290	ns
			4.5 V		20	46		69		58	
			6 V		15	39		59		49	
	CLK	Q or $\overline{\text{Q}}$	2 V		70	175		250		220	
			4.5 V		20	35		50		44	
			6 V		15	30		42		37	
t _t		Q or $\overline{\text{Q}}$	2 V		28	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance per flip-flop	No load	35	pF

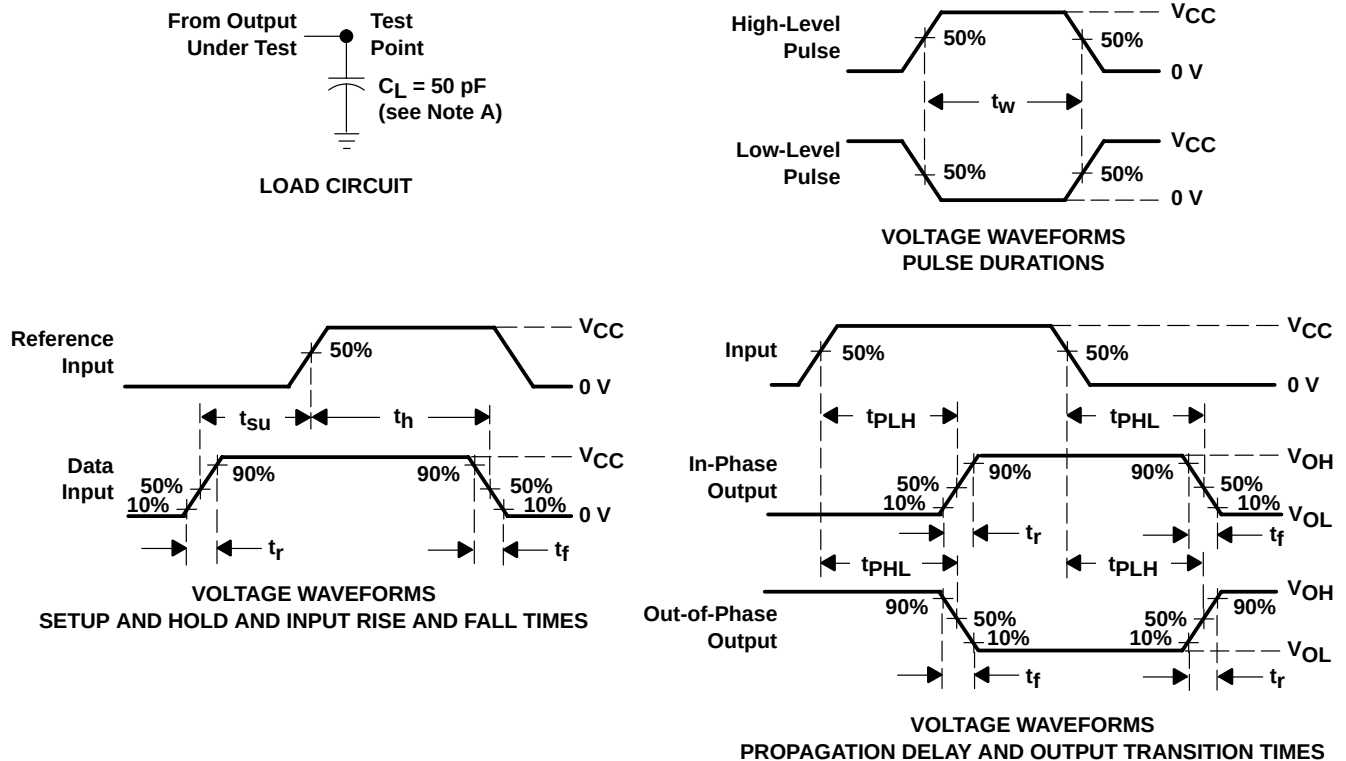


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PARAMETER MEASUREMENT INFORMATION



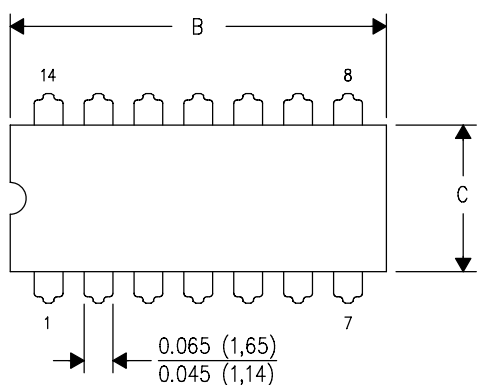
- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 - C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

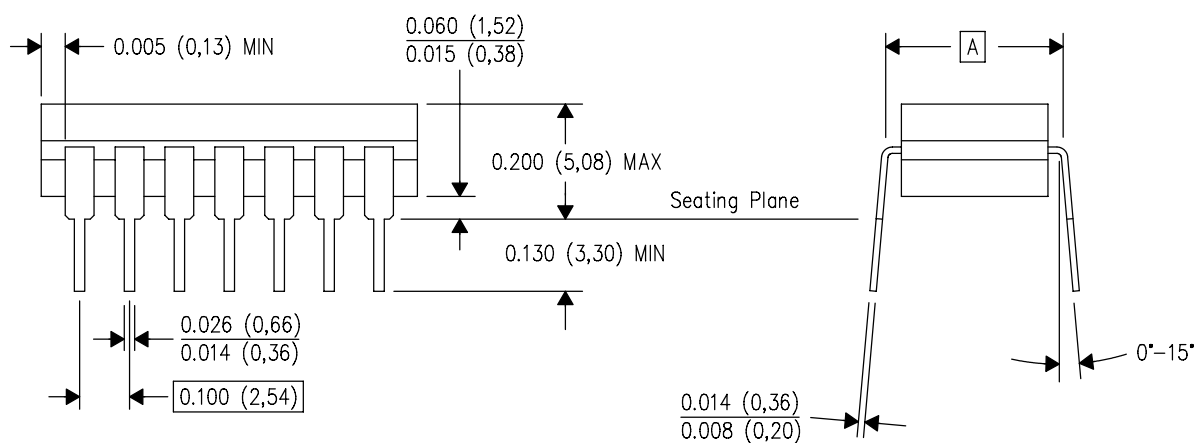
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



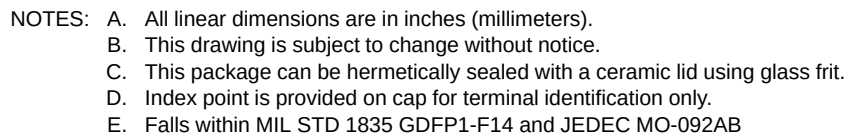
PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

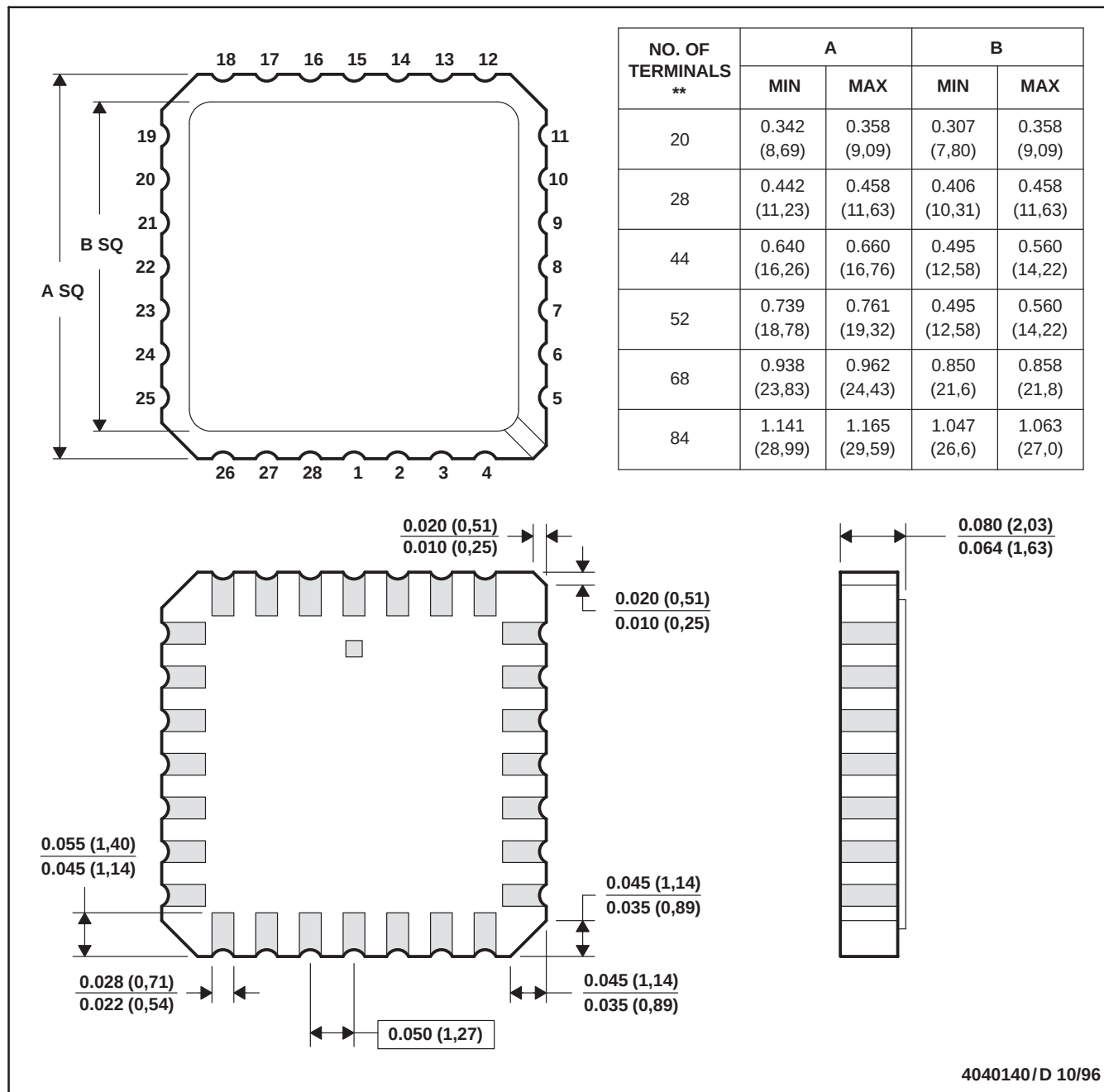
CERAMIC DUAL FLATPACK



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

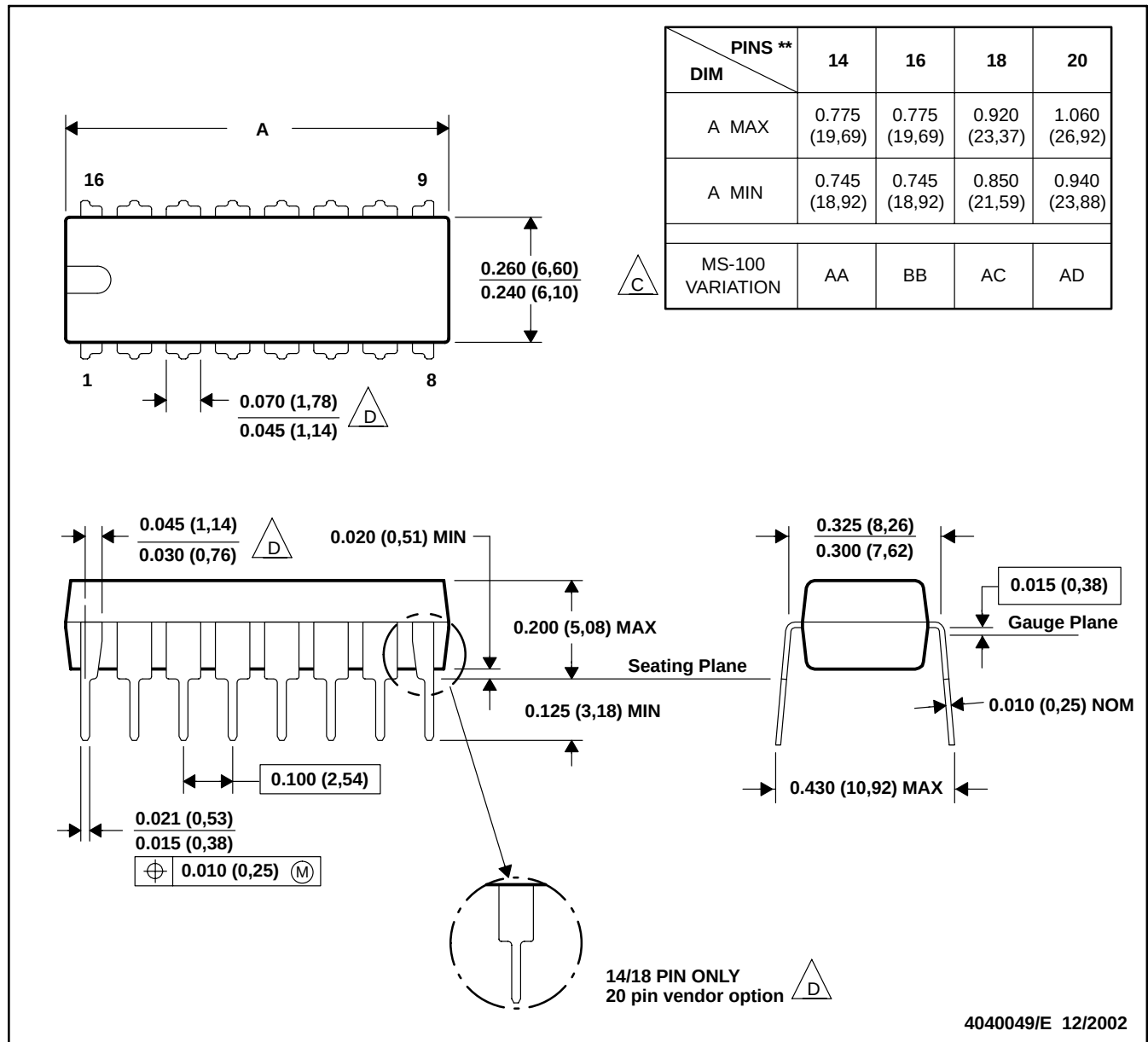


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

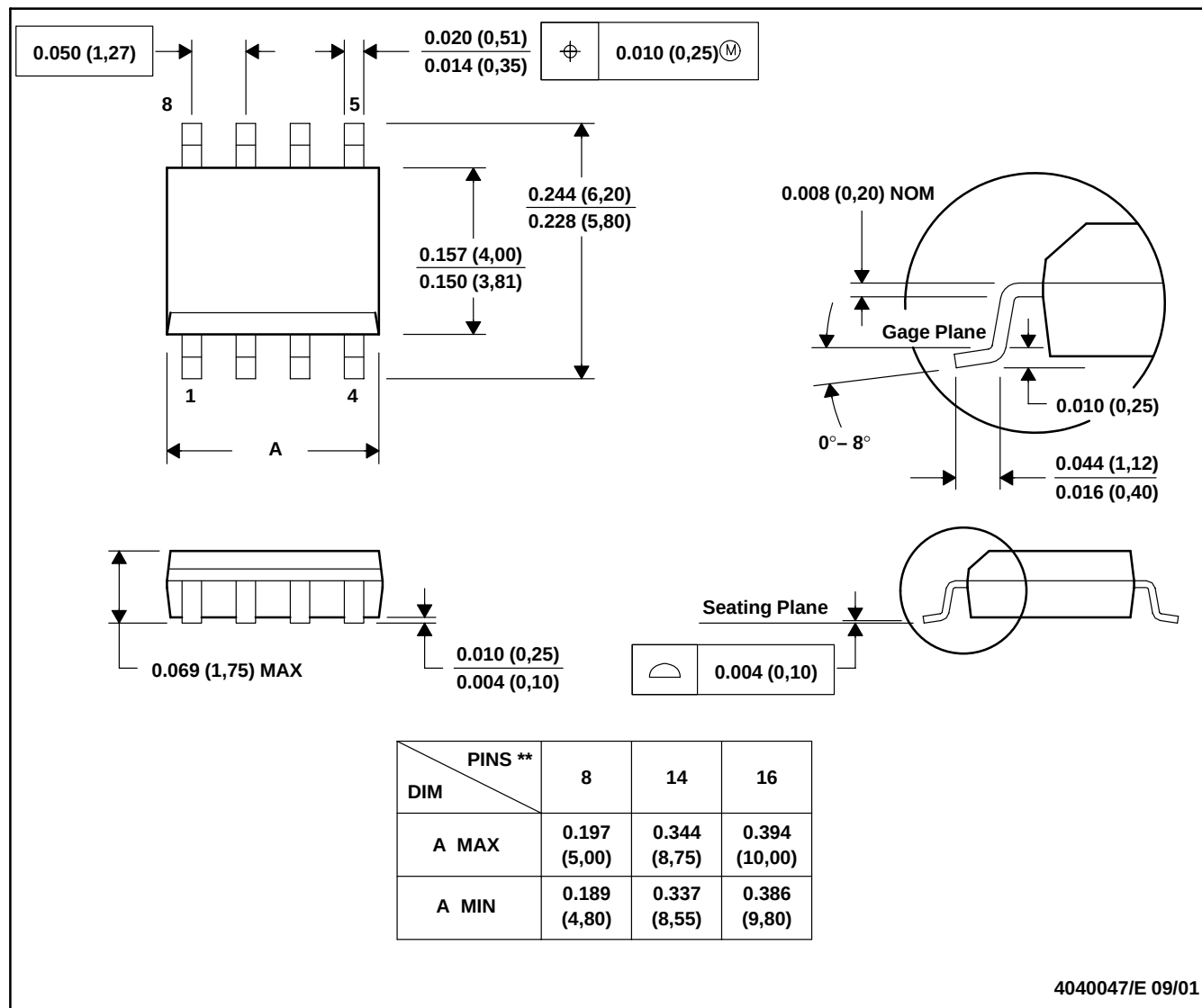


NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G)****PLASTIC SMALL-OUTLINE PACKAGE****8 PINS SHOWN**

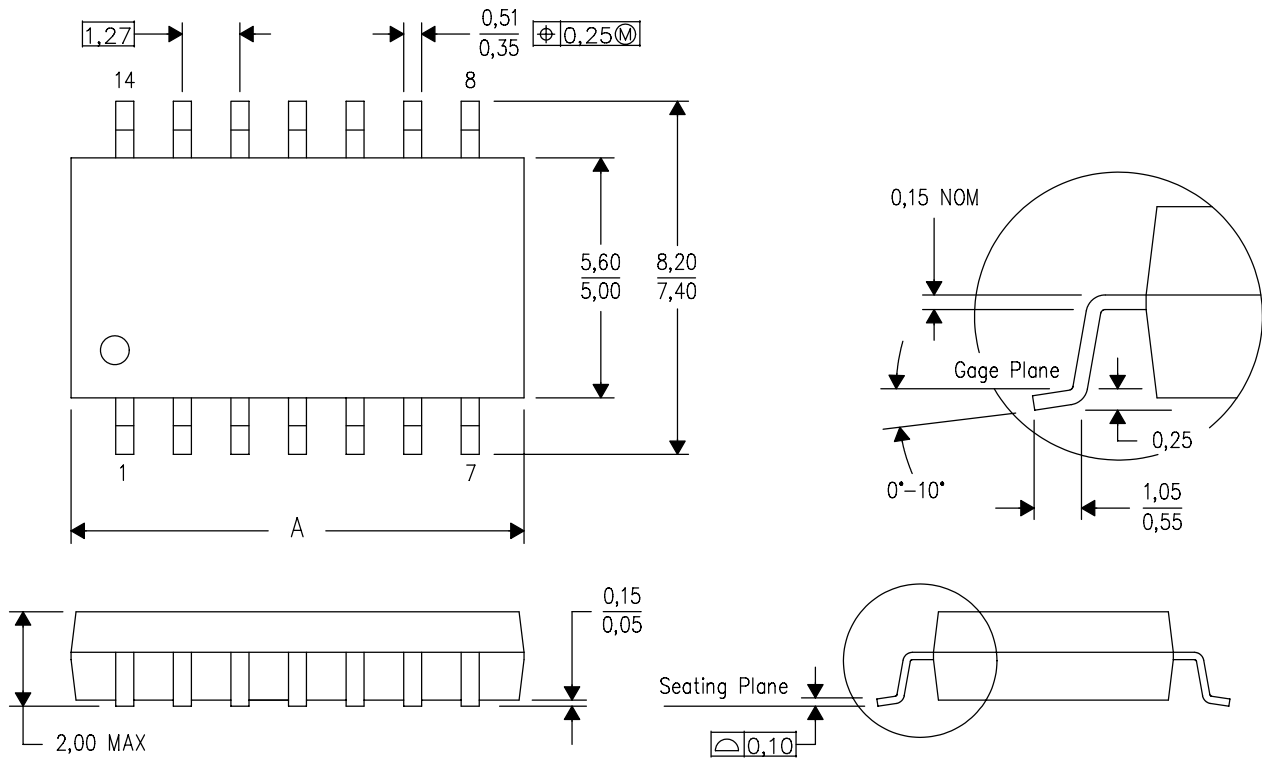
- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

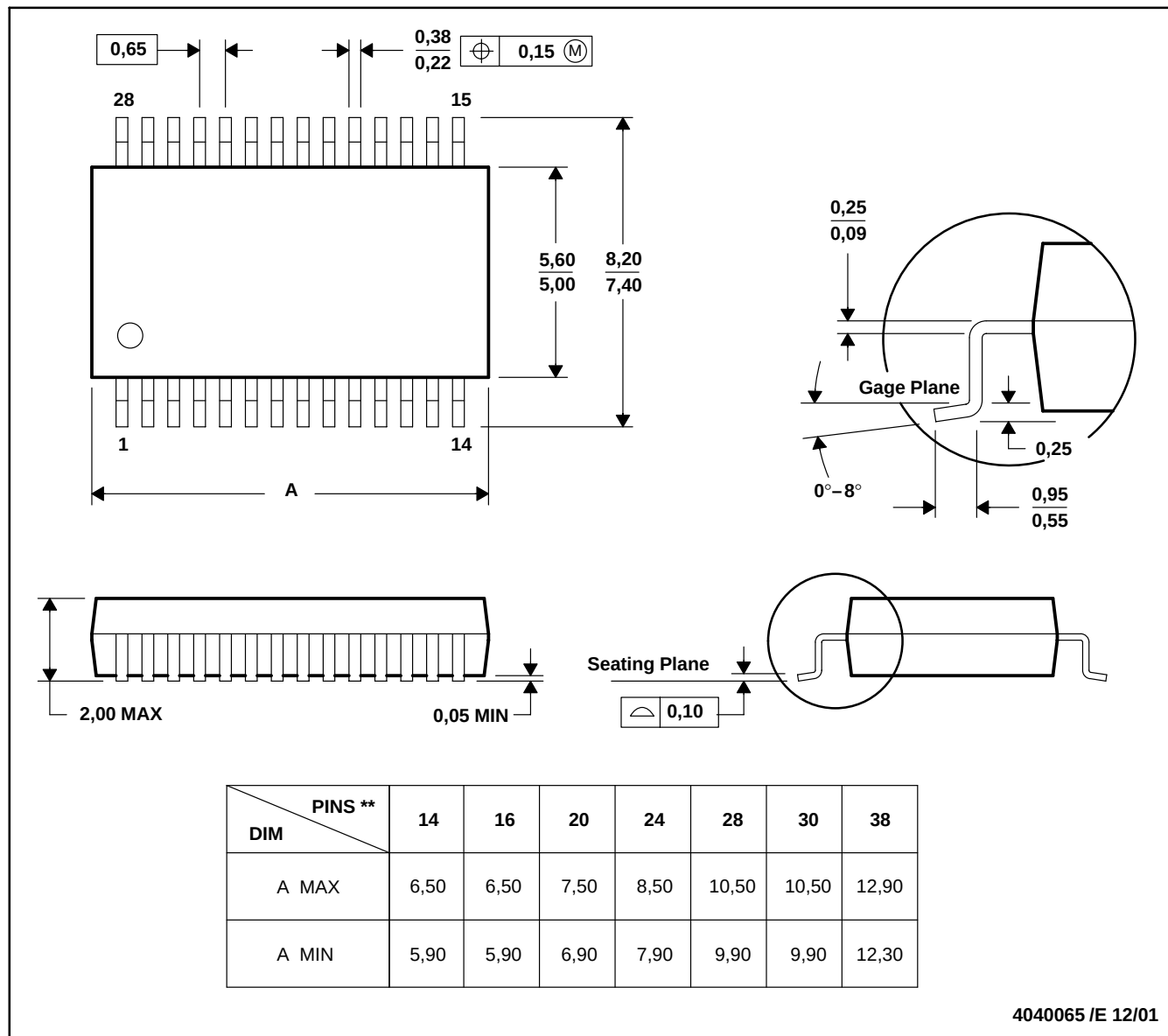
4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN

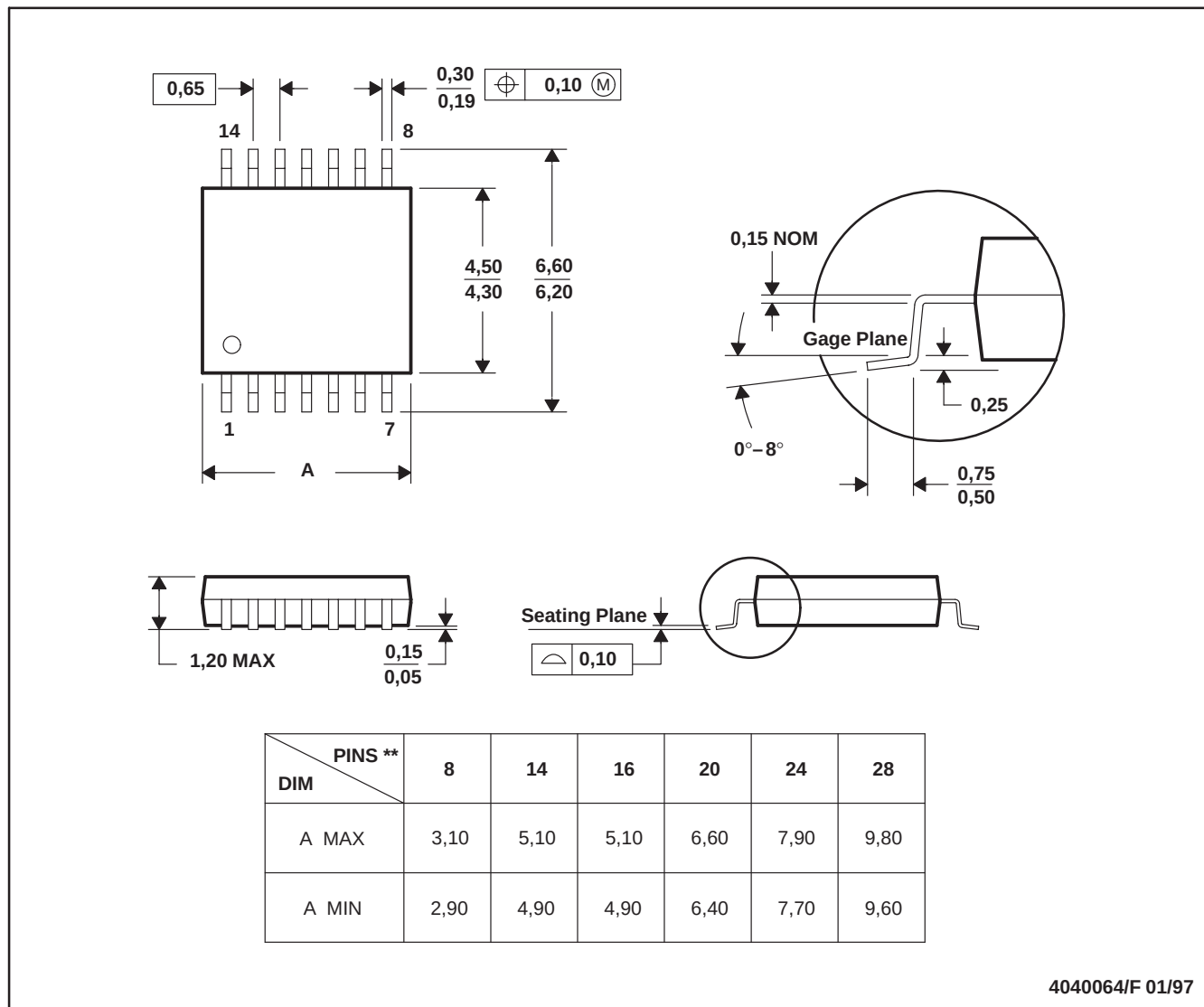


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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